

# N-Channel 60-V (D-S) MOSFET

| PRODUCT SUMMARY     |                                  |                                 |                       |  |  |  |
|---------------------|----------------------------------|---------------------------------|-----------------------|--|--|--|
| V <sub>DS</sub> (V) | $R_{DS(on)}\left(\Omega\right)$  | I <sub>D</sub> (A) <sup>a</sup> | Q <sub>g</sub> (Typ.) |  |  |  |
| 60                  | 0.075 at V <sub>GS</sub> = 10 V  | 4.0                             | 2.1 nC                |  |  |  |
| 60                  | 0.086 at V <sub>GS</sub> = 4.5 V | 3.8                             | 2.1 110               |  |  |  |

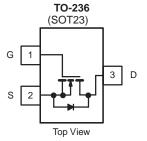
#### **FEATURES**

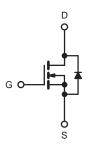
- Halogen-free According to IEC 61249-2-21 Available
- TrenchFET® Power MOSFET
- 100 % R<sub>g</sub> Tested
- 100 % UIS Tested

# HALOGEN FREE

#### **APPLICATIONS**

- Battery Switch
- DC/DC Converter





N-Channel MOSFET

| ABSOLUTE MAXIMUM RATINGS $T_A = 1$                  | 25 °C, unless oth      | erwise noted                      |                      |    |  |
|---|------------------------|-----------------------------------|----------------------|----|--|
| Parameter   | Symbol                 | Limit                             | Unit                 |    |  |
| Drain-Source Voltage                                | V <sub>DS</sub>        | 60                                | V                    |    |  |
| Gate-Source Voltage                                 |                        | $V_{GS}$                          | ± 20                 |    |  |
|   | T <sub>C</sub> = 25 °C |                                   | 4.0                  |    |  |
| Continuous Drain Current (T <sub>.1</sub> = 150 °C) | T <sub>C</sub> = 70 °C | I_                                | 3.4                  |    |  |
| Continuous Diam Current (1) = 150°C)                | T <sub>A</sub> = 25 °C | 'D                                | 3.1 <sup>b, c</sup>  |    |  |
|   | T <sub>A</sub> = 70 °C |                                   | 2.5 <sup>b, c</sup>  | A  |  |
| Pulsed Drain Current                                |                        | I <sub>DM</sub>                   | 12                   | ^  |  |
| Continuous Source-Drain Diode Current               | T <sub>C</sub> = 25 °C | 1-                                | 1.39                 |    |  |
| Continuous Source-Drain Diode Current               | T <sub>A</sub> = 25 °C | ls -                              | 0.91 <sup>b, c</sup> |    |  |
| Avalanche Current                                   | L = 0.1 mH             | I <sub>AS</sub>                   | 6                    |    |  |
| Single-Pulse Avalanche Energy                       | L = 0.1 IIII           | E <sub>AS</sub>                   | 1.8                  | mJ |  |
|   | T <sub>C</sub> = 25 °C | D                                 | 1.66                 |    |  |
| Maximum Bower Discination                           | T <sub>C</sub> = 70 °C |                                   | 1.06                 | W  |  |
| Maximum Power Dissipation                           | T <sub>A</sub> = 25 °C | P <sub>D</sub>                    | 1.09 <sup>b, c</sup> | VV |  |
|   | T <sub>A</sub> = 70 °C |                                   | 0.7 <sup>b, c</sup>  |    |  |
| Operating Junction and Storage Temperature Range    |                        | T <sub>J</sub> , T <sub>stg</sub> | - 55 to 150          | °C |  |

| THERMAL RESISTANCE RATINGS                  |              |                   |         |      |      |  |
|---|--------------|-------------------|---------|------|------|--|
| Parameter                                   | Symbol       | Typical           | Maximum | Unit |      |  |
| Maximum Junction-to-Ambient <sup>b, d</sup> | ≤ 5 s        | R <sub>thJA</sub> | 90      | 115  | °C/W |  |
| Maximum Junction-to-Foot (Drain)            | Steady State | R <sub>thJF</sub> | 60      | 75   | C/VV |  |

- a. Based on T<sub>C</sub> = 25 °C.
  b. Surface Mounted on 1" x 1" FR4 board.
- d. Maximum under Steady State conditions is 120 °C/W.



| Parameter                                     | Symbol                    | Test Conditions   | Min. | Тур.  | Max.  | Unit  |
|---|---------------------------|---|------|-------|-------|-------|
| Static  |                           |   |      |       | L     |       |
| Drain-Source Breakdown Voltage                | V <sub>DS</sub>           | $V_{DS} = 0 \text{ V}, I_{D} = 250 \mu\text{A}$   | 60   |       |       | V     |
| V <sub>DS</sub> Temperature Coefficient       | $\Delta V_{DS}/T_{J}$     |   |      | 55    |       | mV/°C |
| V <sub>GS(th)</sub> Temperature Coefficient   | $\Delta V_{GS(th)}/T_{J}$ | I <sub>D</sub> = 250 μA   |      | - 5   |       |       |
| Gate-Source Threshold Voltage                 | V <sub>GS(th)</sub>       | $V_{DS} = V_{GS}, I_D = 250 \mu A$  | 1    |       | 3     | V     |
| Gate-Source Leakage                           | I <sub>GSS</sub>          | $V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$   |      |       | ± 100 | nA    |
| Zana Oata Wallana Basin Oamani                |                           | $V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}$   |      |       | 1     | μA    |
| Zero Gate Voltage Drain Current               | I <sub>DSS</sub>          | V <sub>DS</sub> = 60 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 55 °C                       |      |       | 10    |       |
| On-State Drain Current <sup>a</sup>           | I <sub>D(on)</sub>        | $V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$   | 8    |       |       | Α     |
|   | В                         | V <sub>GS</sub> = 10 V, I <sub>D</sub> = 1.9 A  |      | 0.075 |       | _     |
| Drain-Source On-State Resistance <sup>a</sup> | R <sub>DS(on)</sub>       | $V_{GS} = 4.5 \text{ V}, I_D = 1.7 \text{ A}$   |      | 0.086 |       | Ω     |
| Forward Transconductance <sup>a</sup>         | 9 <sub>fs</sub>           | V <sub>DS</sub> = 15V, I <sub>D</sub> = 1.9 A   |      | 5     |       | S     |
| Dynamic <sup>b</sup>                          |                           |   |      | 1     | I.    |       |
| Input Capacitance                             | C <sub>iss</sub>          |   |      | 180   |       |       |
| Output Capacitance                            | C <sub>oss</sub>          |   |      | 22    |       |       |
| Reverse Transfer Capacitance                  | C <sub>rss</sub>          | $V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$                            |      | 13    |       | pF    |
| Total Oats Observe                            |                           | V <sub>DS</sub> = 30 V, V <sub>GS</sub> = 10 V, I <sub>D</sub> = 1.9 A                      |      | 4.2   | 6.1   |       |
| Total Gate Charge                             | $Q_g$                     |   |      | 2.1   | 3.2   | nC    |
| Gate-Source Charge                            | $Q_{gs}$                  | $V_{DS} = 30 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 1.9 \text{ A}$                      |      | 0.7   |       |       |
| Gate-Drain Charge                             | $Q_{gd}$                  |   |      | 1     |       |       |
| Gate Resistance                               | $R_{g}$                   | f = 1 MHz   | 0.6  | 2.2   | 5.1   | Ω     |
| Turn-On Delay Time                            | t <sub>d(on)</sub>        |   |      | 4     | 6     | - ns  |
| Rise Time                                     | t <sub>r</sub>            | $V_{DD} = 30 \text{ V}, R_L = 20 \Omega$  |      | 10    | 15    |       |
| Turn-Off Delay Time                           | t <sub>d(off)</sub>       | $I_D\cong$ 1.5 A, $V_{GEN}$ = 10 V, $R_G$ = 1 $\Omega$                                      |      | 10    | 15    |       |
| Fall Time                                     | t <sub>f</sub>            |   |      | 7     | 10.5  |       |
| Turn-On Delay Time                            | t <sub>d(on)</sub>        |   |      | 15    | 23    |       |
| Rise Time                                     | t <sub>r</sub>            | $V_{DD}$ = 30 V, $R_L$ = 20 $\Omega$  |      | 16    | 24    |       |
| Turn-Off Delay Time                           | t <sub>d(off)</sub>       | $I_D = 1.5 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_G = 1 \Omega$                              |      | 11    | 17    | ns    |
| Fall Time                                     | t <sub>f</sub>            |   |      | 11    | 17    |       |
| <b>Drain-Source Body Diode Characteristic</b> | cs                        |   |      |       |       |       |
| Continuous Source-Drain Diode Current         | I <sub>S</sub>            | T <sub>C</sub> = 25 °C  |      |       | 2.19  | ۸     |
| Pulse Diode Forward Current <sup>a</sup>      | I <sub>SM</sub>           |   |      |       | 7     | A     |
| Body Diode Voltage                            | V <sub>SD</sub>           | I <sub>S</sub> = 1.5 A  |      | 0.8   | 1.2   | V     |
| Body Diode Reverse Recovery Time              | t <sub>rr</sub>           |   |      | 15    | 23    | ns    |
| Body Diode Reverse Recovery Charge            | Q <sub>rr</sub>           | 1 45 A 31/31 400 A/ T 67-00   |      | 10    | 15    | nC    |
| Reverse Recovery Fall Time                    | t <sub>a</sub>            | $I_F = 1.5 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$ |      | 12    |       |       |
| Reverse Recovery Rise Time                    | t <sub>b</sub>            |   |      | 3     |       | ns    |

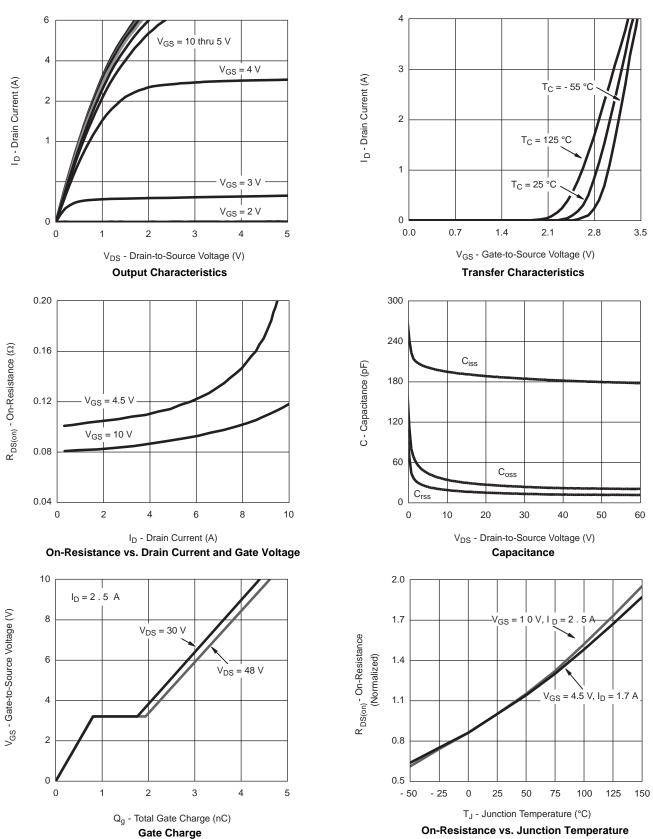
#### Notes:

- a. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %. b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

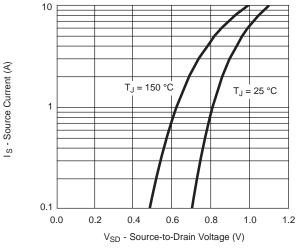


#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

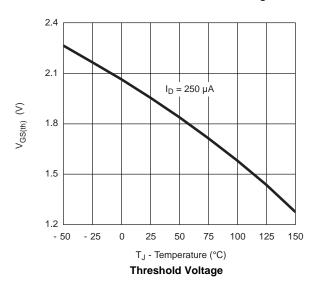




#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

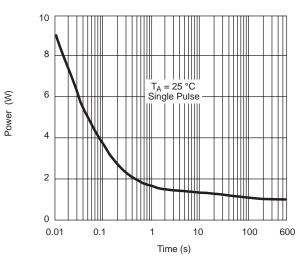


#### Source-Drain Diode Forward Voltage

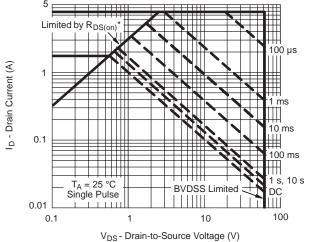


0.35 I<sub>D</sub> = 2.5 A 0.25  $R_{DS(on)}$  - On-Resistance ( $\Omega$ ) T<sub>J</sub> = 125 °C 0.20 0.15 T<sub>J</sub> = 25 °C 0.10 3 6 7 10

V<sub>GS</sub> - Gate-to-Source Voltage (V) On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power

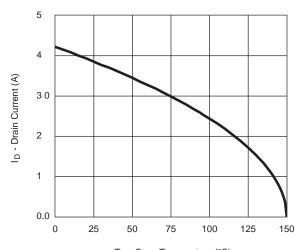


Safe Operating Area

<sup>\*</sup>  $V_{GS}$  > minimum  $V_{GS}$  at which  $R_{DS(on)}$  is specified

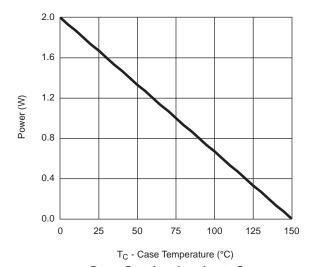


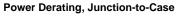
#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

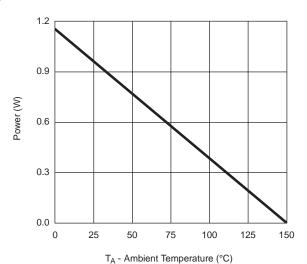


T<sub>C</sub> - Case Temperature (°C)

#### Current Derating\*





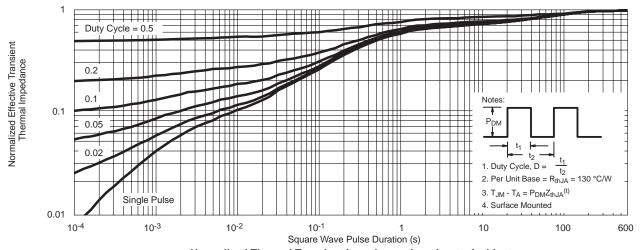


Power Derating, Junction-to-Ambient

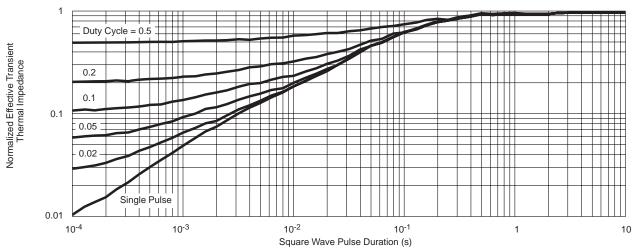
<sup>\*</sup> The power dissipation  $P_D$  is based on  $T_{J(max.)}$  = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



#### **THERMAL RATINGS** ( $T_A = 25$ °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient

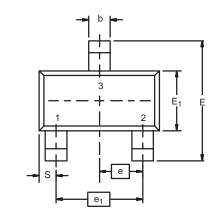


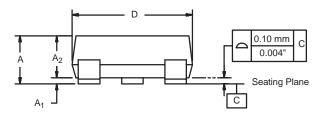
Normalized Thermal Transient Impedance, Junction-to-Foot

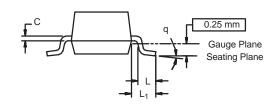


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### SOT-23 (TO-236): 3-LEAD







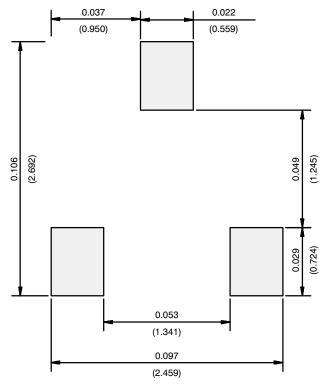
| Dim            | MILLIMETERS |          | INCHES    |            |  |  |
|----------------|-------------|----------|-----------|------------|--|--|
|                | Min         | Max      | Min       | Max        |  |  |
| Α              | 0.89        | 1.12     | 0.035     | 0.044      |  |  |
| A <sub>1</sub> | 0.01        | 0.10     | 0.0004    | 0.004      |  |  |
| A <sub>2</sub> | 0.88        | 1.02     | 0.0346    | 0.040      |  |  |
| b              | 0.35        | 0.50     | 0.014     | 0.020      |  |  |
| С              | 0.085       | 0.18     | 0.003     | 0.007      |  |  |
| D              | 2.80        | 3.04     | 0.110     | 0.120      |  |  |
| E              | 2.10        | 2.64     | 0.083     | 0.104      |  |  |
| E <sub>1</sub> | 1.20        | 1.40     | 0.047     | 0.055      |  |  |
| е              | 0.95        | 0.95 BSC |           | 0.0374 Ref |  |  |
| e <sub>1</sub> | 1.90        | 1.90 BSC |           | 0.0748 Ref |  |  |
| L,             | 0.40        | 0.60     | 0.016     | 0.024      |  |  |
| L <sub>1</sub> | 0.64 Ref    |          | 0.025 Ref |            |  |  |
| S              | 0.50 Ref    |          | 0.020     | Ref        |  |  |
| q              | 3°          | 8°       | 3°        | 8°         |  |  |

ECN: S-03946-Rev. K, 09-Jul-01

DWG: 5479



#### **RECOMMENDED MINIMUM PADS FOR SOT-23**



Recommended Minimum Pads Dimensions in Inches/(mm)



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TK16J60W,S1VQ(O 2SK2614(TE16L1,Q) DMN1017UCP3-7 DMN1053UCP4-7 SQJ469EP-T1-GE3 NTE2384 DMC2700UDMQ-7
DMN2080UCB4-7 DMN61D9UWQ-13 US6M2GTR DMN31D5UDJ-7 DMP22D4UFO-7B DMN1006UCA6-7 DMN16M9UCA6-7
STF5N65M6 IRF40H233XTMA1 STU5N65M6 DMN6022SSD-13 DMN13M9UCA6-7 DMTH10H4M6SPS-13 DMN2990UFB-7B
IPB80P04P405ATMA2 2N7002W-G MCAC30N06Y-TP MCQ7328-TP BXP7N65D BXP4N65F AOL1454G WMJ80N60C4 BXP2N20L
BXP2N65D BXT1150N10J BXT1700P06M TSM60NB380CP ROG RQ7L055BGTCR DMNH15H110SK3-13 SLF10N65ABV2
BSO203SP BSO211P IPA60R230P6 IPA60R460CE